

Title (en)
ARRANGEMENT COMPOSED OF AN ELECTRICAL COMPONENT ON A SUBSTRATE, AND METHOD FOR THE PRODUCTION OF SAID ARRANGEMENT

Title (de)
ANORDNUNG AUS EINEM ELEKTRISCHEN BAUELEMENT AUF EINEM SUBSTRAT UND VERFAHREN ZUM HERSTELLEN DER ANORDNUNG

Title (fr)
ENSEMBLE CONSTITUE D'UN COMPOSANT ELECTRIQUE SUR UN SUBSTRAT ET SON PROCEDE DE PRODUCTION

Publication
EP 1609184 A1 20051228 (DE)

Application
EP 04718634 A 20040309

Priority
• EP 2004002424 W 20040309
• DE 10314172 A 20030328

Abstract (en)
[origin: WO2004086502A1] The invention relates to an arrangement comprising at least one substrate (1), at least one electrical component (2) that is disposed on a surface section (11) of the substrate and is provided with an electrical contact area (21), and at least one electrical contact lug (3) having an electrical connecting area (32) for electrically contacting the contact area of the component. The connecting area of the contact lug and the contact area of the component are interconnected in such a way that at least one zone (33) of the contact lug protrudes beyond the contact area of the component. The arrangement is characterized in that the contact lug is provided with at least one electrically conducting film (7) while said electrically conducting film is provided with the electrical connecting area of the contact lug. The inventive arrangement is used particularly for the large-area, low-inductive contacting of power semiconductor chips, which allows for high current density.

IPC 1-7
H01L 23/538; H01L 23/498; H01L 23/66

IPC 8 full level
H01L 21/60 (2006.01); **H01L 23/12** (2006.01); **H01L 23/485** (2006.01); **H01L 23/498** (2006.01); **H01L 23/538** (2006.01); **H01L 23/552** (2006.01); **H01L 23/66** (2006.01)

CPC (source: EP US)
H01L 23/49844 (2013.01 - EP US); **H01L 23/5389** (2013.01 - EP US); **H01L 23/552** (2013.01 - EP US); **H01L 24/24** (2013.01 - EP US); **H01L 24/36** (2013.01 - US); **H01L 24/40** (2013.01 - EP US); **H01L 24/50** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H01L 24/86** (2013.01 - EP US); **H01L 24/97** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US); **H01L 2224/73267** (2013.01 - EP US); **H01L 2224/97** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01023** (2013.01 - EP US); **H01L 2924/01027** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01058** (2013.01 - EP US); **H01L 2924/01061** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/01327** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/09701** (2013.01 - EP US); **H01L 2924/1305** (2013.01 - EP US); **H01L 2924/13055** (2013.01 - EP US); **H01L 2924/13091** (2013.01 - EP US); **H01L 2924/30107** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

C-Set (source: EP US)

EP
1. **H01L 2224/97 + H01L 2224/82**
2. **H01L 2224/45124 + H01L 2924/00**
3. **H01L 2924/00014 + H01L 2224/48**
4. **H01L 2924/1305 + H01L 2924/00**
5. **H01L 2924/00014 + H01L 2224/37099**
6. **H01L 2924/00014 + H01L 2224/73221**

US
1. **H01L 2224/97 + H01L 2224/82**
2. **H01L 2224/45124 + H01L 2924/00**
3. **H01L 2924/00014 + H01L 2224/48**
4. **H01L 2924/1305 + H01L 2924/00**
5. **H01L 2924/00014 + H01L 2224/37099**

Citation (examination)
• US 4783695 A 19881108 - EICHELBERGER CHARLES W [US], et al
• WO 0221595 A2 20020314 - INTEL CORP [US]
• See also references of WO 2004086502A1

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